

# CMS40N03V8-HF

**N-Channel  
RoHS Device  
Halogen Free**

## Features

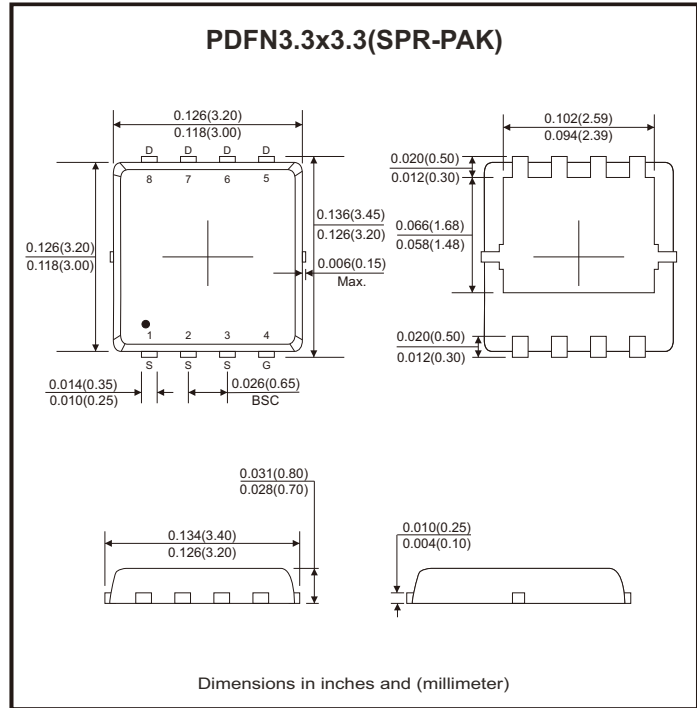
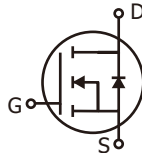
- Low on-resistance.
- Low miller charge.
- Low input capacitance.
- Green device available.
- 100% EAS and 100% Rg guaranteed.

## Mechanical data

- Case: PDFN3.3x3.3/SPR-PAK standard package, molded plastic.

## Circuit diagram

- G : Gate
- S : Source
- D : Drain



## Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
Drain-source voltage		$V_{DS}$	30	V
Gate-source voltage		$V_{GS}$	±20	V
Continuous drain current	$I_D @ T_A = 25^\circ C$		25	A
	$I_D @ T_A = 70^\circ C$		20	
Pulsed drain current (Note 1)		$I_{DM}$	100	A
Continuous drain current (Note 3)	$I_D @ T_C = 25^\circ C$		40	A
	$I_D @ T_C = 70^\circ C$		40	
Total power dissipation	$P_D @ T_C = 25^\circ C$		52	W
	$P_D @ T_A = 25^\circ C$		3.8	
Single pulse avalanche energy, L=0.1mH		$E_{AS}$	72	mJ
Single pulse avalanche current, L=0.1mH		$I_{AS}$	38	A
Operating junction temperature range		$T_J$	-55 to +150	°C
Storage temperature range		$T_{STG}$	-55 to +150	°C
Thermal resistance junction-ambient (Note 2)	$t \leq 10s$	$R_{\theta JA}$	33	°C/W
Thermal resistance junction-case (Note 2)	Steady state	$R_{\theta JC}$	2.4	°C/W

## Electrical Characteristics (at $T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.15		2.2	
Forward transconductance (Note 1)	$g_{fs}$	$V_{DS} = 15V, I_D = 19A$		82		S
Gate-source leakage current	$I_{GSS}$	$V_{GS} = \pm 20V$			$\pm 100$	nA
Drain-source leakage current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$			1	$\mu A$
Static drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 19A$		3.4	4.8	m $\Omega$
		$V_{GS} = 4.5V, I_D = 16A$		4.7	5.8	
Total gate charge	$Q_g$	$I_D = 19A, V_{DS} = 15V, V_{GS} = 4.5V$		12		nC
Gate-source charge	$Q_{gs}$			6		
Gate-drain ("miller") charge	$Q_{gd}$			5		
Turn-on delay time	$t_{d(on)}$	$V_{DS} = 15V, V_{GS} = 4.5V$ $I_D = 10A, R_G = 1\Omega, R_L = 1.5\Omega$		24		nS
Rise time	$t_r$			21		
Turn-off delay time	$t_{d(off)}$			25		
Fall time	$t_f$			17		
Input capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		1750		pF
Output capacitance	$C_{oss}$			360		
Reverse transfer capacitance	$C_{rss}$			150		
Gate resistance	$R_g$	$f = 1MHz$		3.2		$\Omega$
<b>Source-drain diode</b>						
Max. body-diode continuous current	$I_S$				40	A
Diode forward voltage	$V_{SD}$	$I_S = 10A, V_{GS} = 0V$		0.8	1.2	V
Reverse recovery time	$t_{rr}$	$I_F = 10A, T_J = 25^{\circ}\text{C}$		25		nS
Reverse recovery charge	$Q_{rr}$	$di/dt = 100A/\mu s$		17		nC
<b>Guaranteed avalanche characteristics</b>						
Single pulse avalanche energy (Note 4)	EAS	$V_{DD} = 20V, L = 0.1mH, I_{AS} = 31A$	48			mJ

Notes: 1. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .

2.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.  $R_{\theta JA}$  shown below for single device operation on FR-4 in still air.

3. The maximum current rating is limited by package.

4. The min. value is 100% EAS tested guarantee.

## Rating and Characteristic Curves (CMS40N03V8-HF)

Fig.1 - Typical Output Characteristics

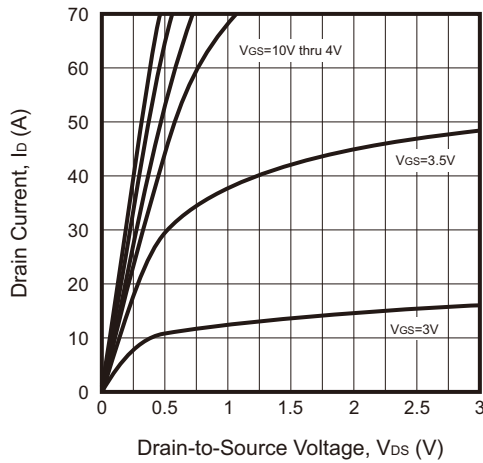


Fig.2 - On-Resistance vs. G-S Voltage

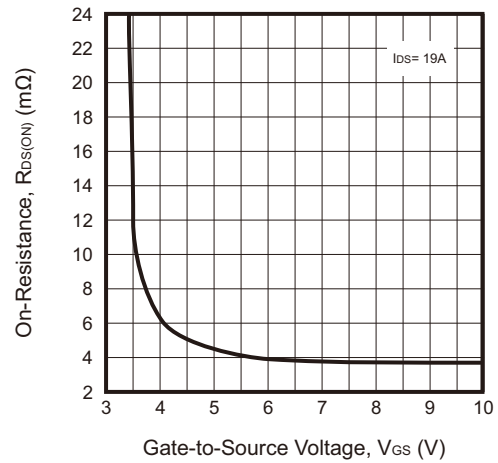


Fig.3 - On-Resistance vs. Drain Current

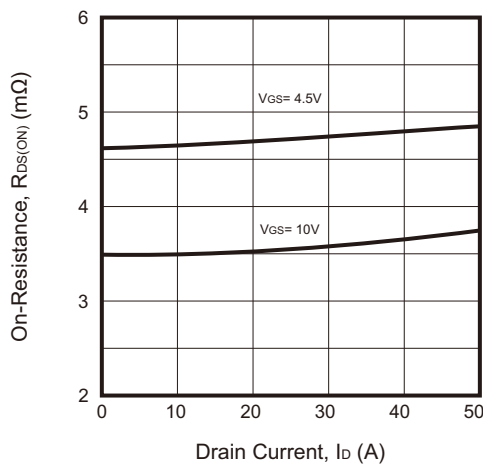


Fig.4 - Normalized  $R_{DS(ON)}$  vs.  $T_J$

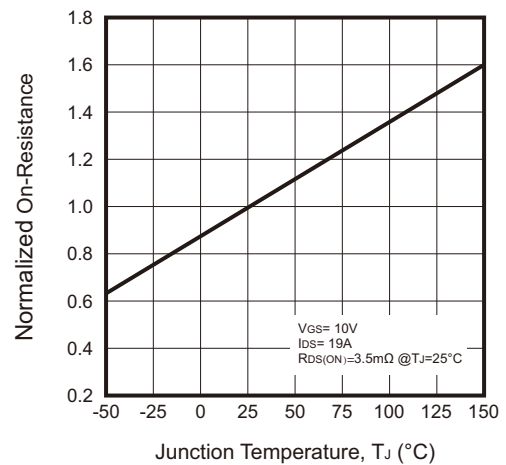


Fig.5 - Normalized  $V_{GS(th)}$  vs.  $T_J$

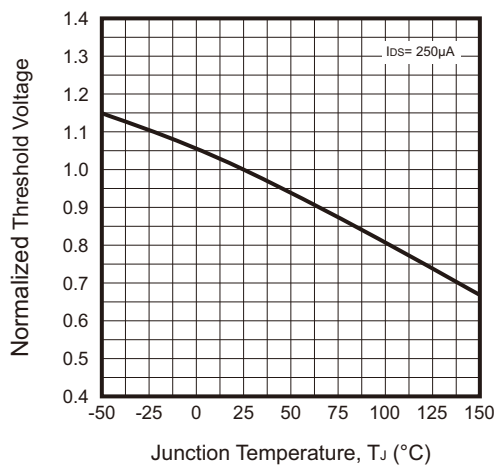
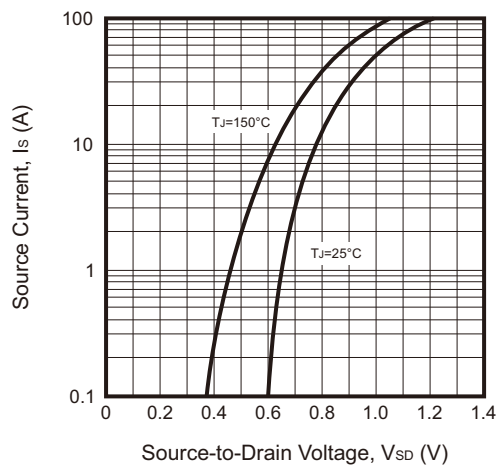


Fig.6 - Forward Characteristics of Reverse



## Rating and Characteristic Curves (CMS40N03V8-HF)

Fig.7 - Gate Charge Characteristics

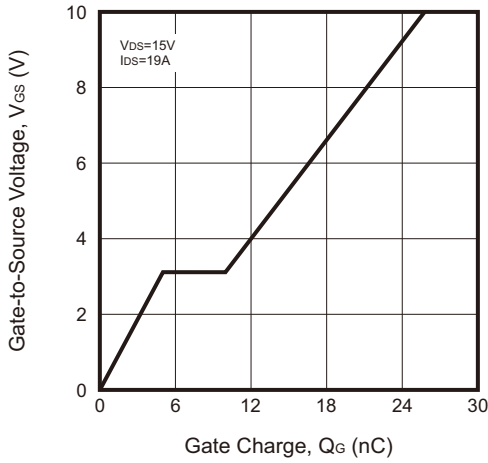


Fig.8 - Capacitance Characteristics

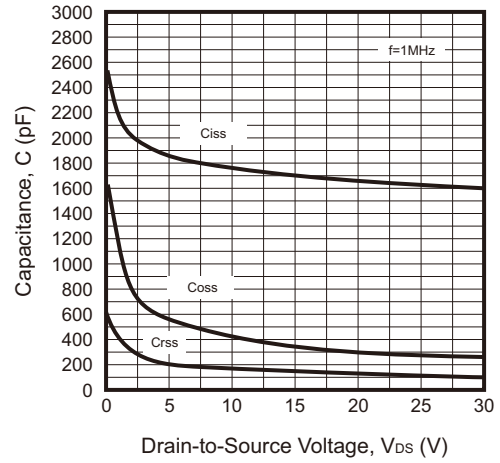


Fig.9 - Safe Operating Area

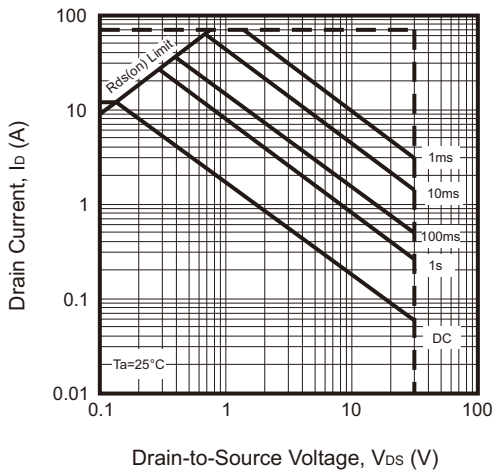


Fig.10 - Power Dissipation

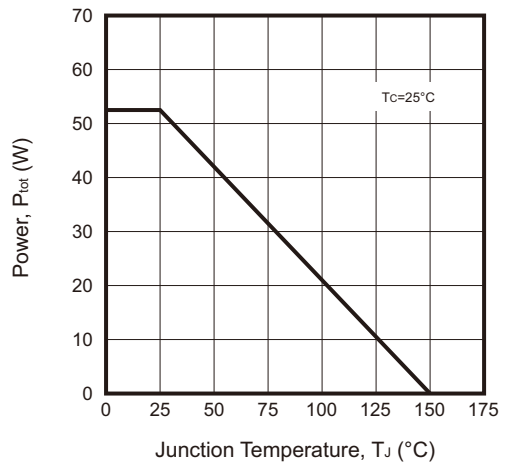
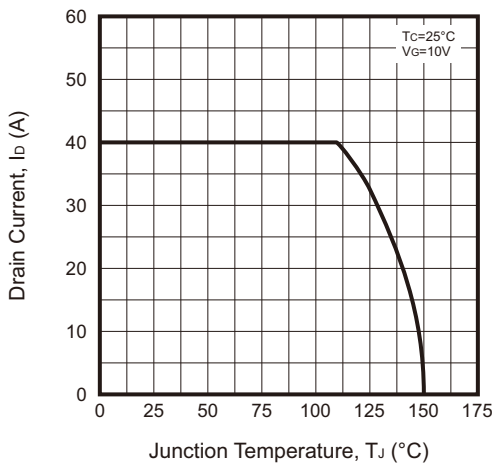
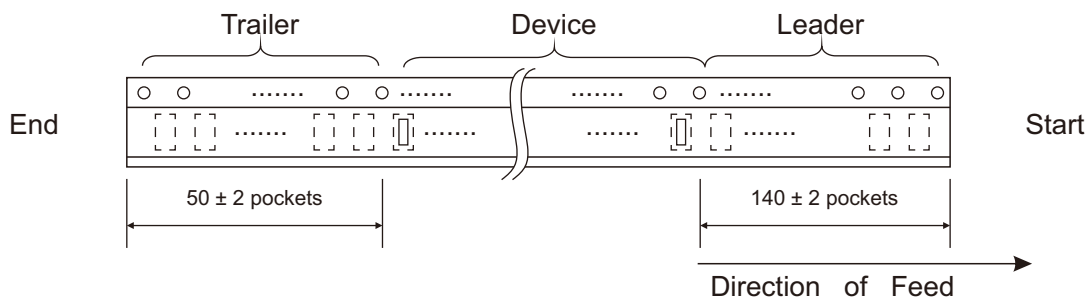
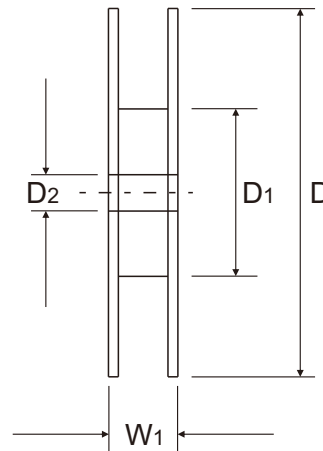
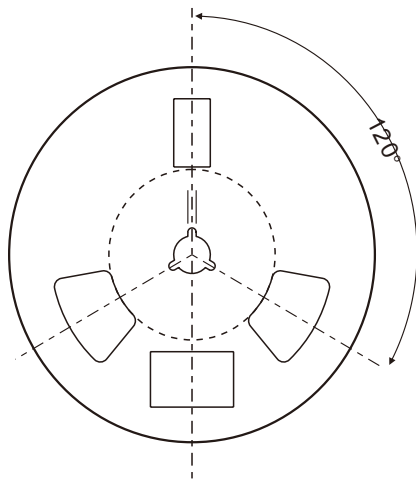
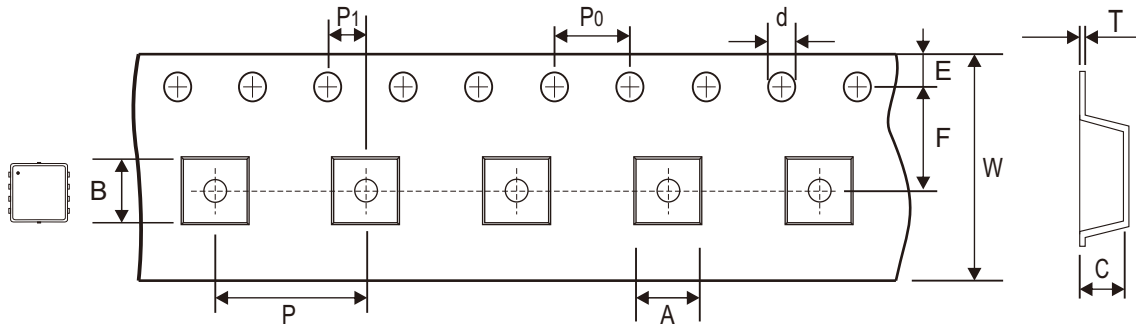


Fig.11 - Drain Current vs. T<sub>J</sub>



Reel Taping Specification



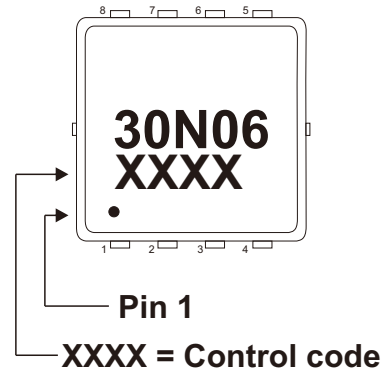
SPR-PAK	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	3.55 ± 0.10	3.55 ± 0.10	1.10 + 0.10 - 0.05	1.50 + 0.10 - 0.00	330.00 ± 1.00	178.00 + 0.00 - 2.00	13.00 min.
	(inch)	0.140 ± 0.004	0.140 ± 0.004	0.043 + 0.004 - 0.002	0.059 + 0.004 - 0.000	12.992 ± 0.039	7.008 + 0.000 - 0.079	0.512 min.

SPR-PAK	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	5.50 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.30 ± 0.05	12.00 + 0.30 - 0.10	18.40 ref.
	(inch)	0.069 ± 0.004	0.217 ± 0.002	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.012 ± 0.002	0.472 + 0.012 - 0.004	0.724 ref.

Company reserves the right to improve product design , functions and reliability without notice. REV:A

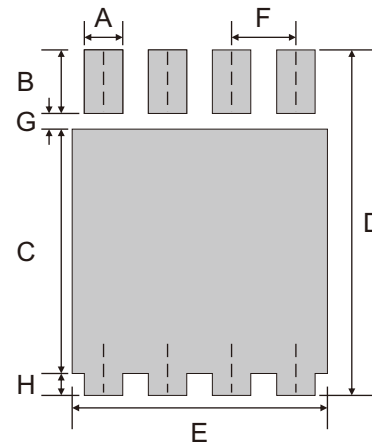
## Marking Code

Part Number	Marking Code
CMS40N03V8-HF	30N06



## Suggested PAD Layout

SIZE	SPR-PAK (PDFN3.3x3.3)	
	(mm)	(inch)
A	0.40	0.016
B	0.60	0.024
C	2.35	0.093
D	3.55	0.140
E	2.80	0.110
F	0.65	0.026
G	0.35	0.014
H	0.25	0.010



Note: 1. The pad layout is for reference purposes only.

## Standard Packaging

Case Type	REEL PACK	
	REEL ( pcs )	Reel Size (inch)
SPR-PAK (PDFN3.3x3.3)	3000	13